



基板取付穴推奨寸法 (t=1.6)  
RECOMMENDED P.C. BOARD  
HOLE DIMENSION (SCALE 5:1)

適合FPC/FFC推奨寸法  
RECOMMENDED FPC/FFC  
厚さ THK : 0.3 ±0.05 (SCALE 5:1)

注記 NOTES

- △ MX J側を基準に奇数番目の極におけるソルダーテール。  
SOLDER TAIL OF ODD CKTS, MXJ MARK AS BASIC.
- △ MX J側を基準に偶数番目の極におけるソルダーテール。  
SOLDER TAIL OF EVEN CKTS, MXJ MARK AS BASIC.
- △ 3極~10極に適用。APPLY FOR 3-10 CKTS.
- △ 3極~19極に適用。APPLY FOR 3-19 CKTS.
- 5. ( ) 内寸法は、参考値。  
( ) DIMENSION IS FOR REFERENCE.
- 6. ソルダーテールは、先端が取付推奨穴にガイドされること。  
SOLDER TAILS MAY BE CHECKED BY INSERTION  
FOR RECOMMENDED PCB BOARD HOLES.
- △ 両端各2本のソルダーテールに適用。  
SOLDER TAIL KINK ON 2 CKTS OF BOTH SIDES ONLY.

9. FPC/FFCについて:  
打抜き方向は導体側から補強板側を推奨いたします。  
ABOUT FPC/FFC  
RECOMMENDED PUNCHER DIRECTION  
: FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
FPCについて:  
補強フィルム材質はポリイミドを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
ABOUT FPC  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

48.25	43.95	39-53-2347	5597-34CPBX7F	34
47	42.7	-2337	-33CPBX7F	33
45.75	41.45	-2327	-32CPBX7F	32
44.5	40.2	-2317	-31CPBX7F	31
43.25	38.95	-2307	-30CPBX7F	30
42	37.7	-2297	-29CPBX7F	29
40.75	36.45	-2287	-28CPBX7F	28
39.5	35.2	-2277	-27CPBX7F	27
38.25	33.95	-2267	-26CPBX7F	26
37	32.7	-2257	-25CPBX7F	25
35.75	31.45	-2247	-24CPBX7F	24
34.5	30.2	-2237	-23CPBX7F	23
33.25	28.95	-2227	-22CPBX7F	22
32	27.7	-2217	-21CPBX7F	21
30.75	26.45	-2207	-20CPBX7F	20
29.5	25.2	-2197	-19CPBX7F	19
28.25	23.95	-2187	-18CPBX7F	18
27	22.7	-2177	-17CPBX7F	17
25.75	21.45	-2167	-16CPBX7F	16
24.5	20.2	-2157	-15CPBX7F	15
23.25	18.95	-2147	-14CPBX7F	14
22	17.7	-2137	-13CPBX7F	13
20.75	16.45	-2127	-12CPBX7F	12
19.5	15.2	-2117	-11CPBX7F	11
17	12.7	-2097	-09CPBX7F	9
15.75	11.45	-2087	-08CPBX7F	8
14.5	10.2	-2077	-07CPBX7F	7
13.25	8.95	-2067	-06CPBX7F	6
12	7.7	-2057	-05CPBX7F	5
10.75	6.45	39-53-2047	5597-04CPBX7F	4
B	A	EDP NO.	ENG NO.	極数

8. 本製品は5597-NCPBXの鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 5597-NCPBX

MODEL NO. 5597-NCPBX7F

材料	HOUSING, ACTUATOR: FBTP, UL94-0
MATERIAL	TERMINAL: PHOSPHOR-BRONZE THK: 0.32t
仕上げ	鍍ヒスマス: 1.0 μm MIN. FINISH TIN-BISMUTH: 1.0 MICROMETER MIN.
	ニッケル下地: 1.0 μm MIN. NICKEL PLATING: 1.0 MICROMETER MIN.
適用電線範囲	—#—
WIRE RANGE	—#—
被覆外径	—#—
INS. RANGE	—#—

REVISED	EC NO: J2016-0714
	DRWN: YMIJUN002 2016/01/08
	CHKD: K. TAKAHASHI 2016/01/06
	APPR: TKUSUHARA01 2016/01/20
DESCRIPTION	
REV	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
0.25 UNDER	UNDER ±0.03
0.25 OVER	0.5 UNDER ±0.05
0.5 OVER	1.0 UNDER ±0.1
1.0 OVER	10 UNDER ±0.2
10 OVER	30 UNDER ±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
M. NAGATA	'04/03/04
CHECKED BY	DATE
K. TOJO	'04/03/04
APPROVED BY	DATE
M. SASAO	'04/03/04
MATERIAL NO.	DOCUMENT NO.
SEE CHART	SD-5597-008
SIZE	A3
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SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
---	METRIC	◎ □
1.25 FPC CONN ASSY ZIF		
-LEAD FREE-		
<b>molex</b>		
DOCUMENT NO.		SHEET NO.
SD-5597-008		1 OF 1